

EAST - [10715990.wsp:1]

File View Edit Tools Window Help

Drafts
 Pending
 Active
 L1: (1174259) wirenear bond\$3
 L2: (52464) wire near bond\$3
 L3: (756) 2 and (wire near loop)
 L4: (21) 3 and (crush\$2)
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DBs: USPAT:EPO, JPO, DERWENT:IBM_TDB

Default operator: OR

3 and (crush\$2)

Highlight all hit terms initially

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	U	I	Document ID	Issue Date	Pages	Title	Current OR	Current XRef
7	<input type="checkbox"/>	<input type="checkbox"/>	US 6164518 A	20001226	13	Wire bonding method and apparatus	228/102	228/106; 228/180.5;
8	<input type="checkbox"/>	<input type="checkbox"/>	US 6080651 A	20000627	9	Wire bonding method	438/617	228/180.5; 228/904;
9	<input type="checkbox"/>	<input type="checkbox"/>	US 5864174 A	19990126	25	Semiconductor device having a die pad structure for preventing cracks in a molding	257/676	174/52.2; 174/52.4;
10	<input type="checkbox"/>	<input type="checkbox"/>	US 5585600 A	19961217	9	Encapsulated semiconductor chip module and method of forming the same	174/52.4	257/666; 257/667;
11	<input type="checkbox"/>	<input type="checkbox"/>	US 5566876 A	19961022	29	Wire bonder and wire bonding method	228/102	228/104; 228/180.5;
12	<input type="checkbox"/>	<input type="checkbox"/>	US 5474224 A	19951212	30	Wire bonder and wire bonding method	228/102	228/180.5; 228/9;
13	<input type="checkbox"/>	<input type="checkbox"/>	US 5458280 A	19951017	29	Wire bonder and wire bonding method	228/102	228/104; 228/180.5;
14	<input type="checkbox"/>	<input type="checkbox"/>	US 5456403 A	19951010	28	Wire bonder and wire bonding method	228/102	228/180.5; 228/4.5;
15	<input type="checkbox"/>	<input type="checkbox"/>	US 5299729 A	19940405	22	Method of forming a bump electrode and manufacturing a resin-encapsulated	228/180.22	257/E21.508; 257/E23.021;
16	<input type="checkbox"/>	<input type="checkbox"/>	US 5238173 A	19930824	18	Wire bonding misattachment detection apparatus and that detection method in a	228/104	228/4.5
17	<input type="checkbox"/>	<input type="checkbox"/>	US 5172851 A	19921222	22	Method of forming a bump electrode and manufacturing a resin-encapsulated	228/180.22	228/4.5; 257/E21.508;